



XC540203CZT75A :Part Detail

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General Information

Part Number	XC540203CZT75A
Description	HALIDE-FREE PACKAGE KIT W/LEAD SPHERE
Product Line	SGT823EA
PTI	MBGC
Material Type	Tested Packaged Device
Life Cycle Description (code)	PRODUCT LAST SHIPMENTS
Status	No Longer Manufactured
Application/Qualification Tier	AUTO; >=10 YEARS APPLICATION LIFE

Package Information

Package Type and Termination Count	PBGA 256
Package Description and Mechanical Drawing	PBGA 256 23*23*1.22P1.27
Device Weight(g)	1.72405
Package Material	Plastic
Mounting Style	Surface Mount
Package Length (nominal)(mm)	23.000
Package Width (nominal)(mm)	23.000
Package Thickness (nominal)(mm)	2.540
Tape & Reel	No

Environmental and Compliance Information

Pb-Free	No
RoHS Compliant	No
Halogen Free	Yes
Material Composition Declaration (MCD)	Download MCD Report Download MCD Report
RoHS Certificate of Analysis (CoA)	Download RoHS CoA Report
Moisture Sensitivity Level (MSL)	3

Peak Package Body Temperature (PPT)(°C)	220
Maximum Time at Peak Temperature (s)	30
Number of Reflow Cycles	3
REACH SVHC	NXP REACH Statement
UL94 (plastics flammability test)	V0;Burning stops within 10 seconds on a vertical specimen;no drips allowed

Manufacturing Information

Micron Size(μm)	.32
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Ordering Information

Last Order Date	21 Nov 2014
Last Ship Date	21 Nov 2015
Minimum Package Quantity (MPQ)	300
MPQ Container	BRICK
Exempt from Minimum Delivery Value	Yes
Preferred Order Quantity (POQ)	300
POQ Container	BOX
Export Control Classification Number (US)	3A991A2
Harmonized Tariff (	
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US Currency	-
Device Sample Availability	01 Feb 2006
Device Production Availability	01 Feb 2006
Order	

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
15939	Product Discontinuance	END OF LIFE OF SELECT MICROCONTROLLER DEVICES	21 Nov 2013	21 Nov 2013
15066	Product Bulletin	PBGA- Relief Notch Removal	08 Mar 2012	10 Mar 2012
13601	Product Change Notice	FSL (MSG) Transition of Substrate Supplier	10 Jul 2009	13 Nov 2009
P13462	Product Alert	MSG TRANSITION OF PBGA SUBSTRATE SUPPLIER	10 Dec 2008	10 Dec 2008

Operating Characteristics

Sample Exception Availability	N
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Reliability Data Lookup

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